

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



December 2014

FQPF9P25YDTU

P-Channel QFET® MOSFET

-250 V, -6 A, 620 $m\Omega$

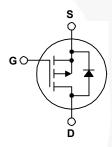
Description

produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, • 100% Avalanche Tested DC motor control, and variable switching power applications.

Features

- This P-Channel enhancement mode power MOSFET is -6 A, -250 V, $R_{DS(on)}$ = 620 m Ω (Max.) @ V_{GS} = -10 V,
 - Low Gate Charge (Typ. 29 nC)
 - Low Crss (Typ. 27 pF)





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQPF9P25YDTU	Unit		
V _{DSS}	Drain-Source Voltage		-250	V		
I _D	Drain Current - Continuous (T _C = 25°C)		-6.0	Α		
	- Continuous (T _C = 100°C)		-3.9	А		
I _{DM}	Drain Current - Pulsed	(Note 1)	-24	A		
V _{GSS}	Gate-Source Voltage		± 30	V		
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	650	mJ		
I _{AR}	Avalanche Current	(Note 1)	-6.0	Α		
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.0	mJ		
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-5.5	V/ns		
P_{D}	Power Dissipation (T _C = 25°C)		50	W		
	- Derate above 25°C		0.4 W/°			
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C		
T _L	Maximum lead temperature for soldering, 1/8" from case for 5 seconds.		300	°C		

Thermal Characteristics

Symbol	Parameter	FQPF9P25YDTU	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.5	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W	

Packag	je Marki	ng and Ord	ering lı	nforma	ation						
Part Number FQPF9P25YDTU		Top Mark	Pack	Package Packing Method TO-220F (-formed) Tube		Reel	Size	Tape Wi	dth	Quantity	
		FQPF9P25				N/A		N/A		50 units	
Electric	cal Chai	racteristics	T _C = 25°C	C unless other	erwise noted.						
Symbol		Parameter			Test Conditions		Min.	Тур.	Max	. Unit	
Off Cha	aracterist	ice									
BV _{DSS}		rce Breakdown Vol	tane	V _{CC} = 0	V, I _D = -250 μA		-250		_	V	
ΔBV _{DSS}	Breakdown Voltage Temperature					200			•		
/ ΔT _J		Coefficient			I_D = -250 μA, Referenced to 25°C			-0.2		V/°C	
I _{DSS}	Zana Oaka Walkana Busin Oursent			V _{DS} = -250 V, V _{GS} = 0 V					-1	μА	
	Zero Gale	Zero Gate Voltage Drain Current		V _{DS} = -200 V, T _C = 125°C					-10	μΑ	
I _{GSSF}	Gate-Body	/ Leakage Current,	Forward	rd $V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$					-100	nA	
I _{GSSR}	Gate-Body	/ Leakage Current,	Reverse	$V_{GS} = 3$	80 V, V _{DS} = 0 V				100	nA	
On Cha	ıracteristi	ics									
V _{GS(th)}		shold Voltage		V _{DS} = V	/ _{GS} , I _D = -250 μA	-/	-3.0		-5.0	V	
R _{DS(on)}	Static Drai				10 V, I _D = -3.0 A			0.48	0.62	Ω	
9 _{FS}	Forward T	Transconductance		V _{DS} = -	_S = -40 V, I _D = -3.0 A			4.8		S	
Dvnam	ic Charac	teristics		1				+	1		
C _{iss}	Input Capa			V _{DS} = -25 V, V _{GS} = 0 V,				910	1180) pF	
C _{oss}	Output Ca	Capacitance		f = 1.0 MHz			170	220	pF		
C _{rss}	Reverse T	ransfer Capacitano	e	1.0 111112				27	35	pF	
				1							
		cteristics		1							
t _{d(on)}	Turn-On D			V _{DD} = -	V_{DD} = -125 V, I_{D} = -9.4 A, R_{G} = 25 Ω			20	50	ns	
t _r	Turn-On R			$R_{G} = 25$				150	310	ns	
t _{d(off)}	Turn-Off D	•						45	100	ns	
t _f	Turn-Off F				(1)	10le 4)		65	140	ns	
Q_g	Total Gate			V_{DS} = -200 V, I_{D} = -9.4 A, V_{GS} = -10 V (Note 4)				29	38	nC	
Q_{gs}	Gate-Sour	ce Charge						7.6		nC	
Q _{gd}	Gate-Drain	n Charge				lote 4)	/	14		nC	
Droin C	'auraa Di	ada Charastar	iotico c	ad Mass	imum Batinas						
	1	ode Character							-6.0	Λ	
I _S		Continuous Drain-Source Diode Forward Current Pulsed Drain-Source Diode Forward Current					-6.0				
I _{SM}									-24	A	
V _{SD}		rce Diode Forward	voltage		V, I _S = -6.0 A			100	-5.0		
t _{rr}		Recovery Time			0 V, I _S = -9.4 A, = 100 A/μs			190		ns	
Q_{rr}	Reverse R	Recovery Charge		uiF / ul	- 100 Ανμδ			1.45		μС	

Q_{rr}

- 1. Repetitive rating : pulse-width limited by maximum junction temperature.
- 2. L = 28.9 mH, I $_{AS}$ = -6.0 A, V $_{DD}$ = -50 V, R $_{G}$ = 25 Ω , starting T $_{J}$ = 25°C. 3. I $_{SD}$ ≤ -9.4 A, di/dt ≤ 300 A/ μ s , V $_{DD}$ = BV $_{DSS}$, starting T $_{J}$ = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

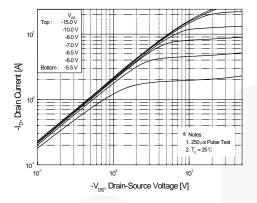


Figure 1. On-Region Characteristics

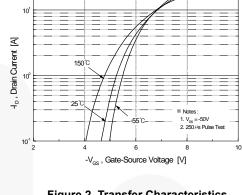


Figure 2. Transfer Characteristics

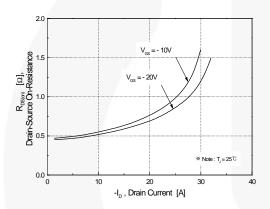


Figure 3. On-Resistance Variation vs. **Drain Current and Gate Voltage**

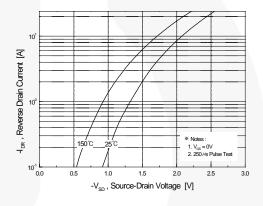


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

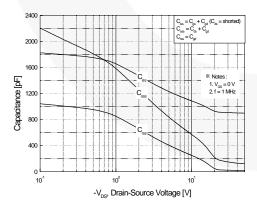


Figure 5. Capacitance Characteristics

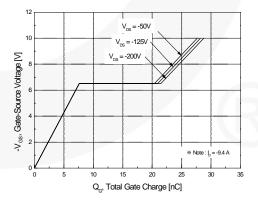
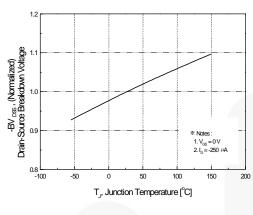


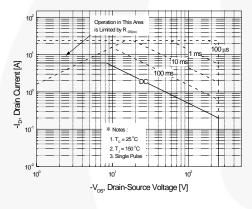
Figure 6. Gate Charge Characteristics



Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



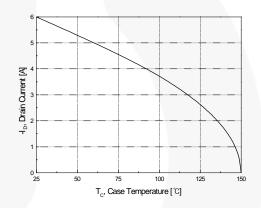


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

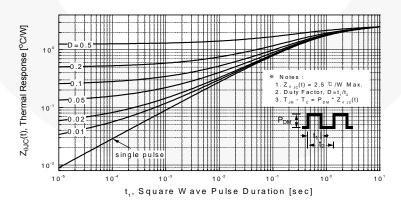


Figure 11. Transient Thermal Response Curve

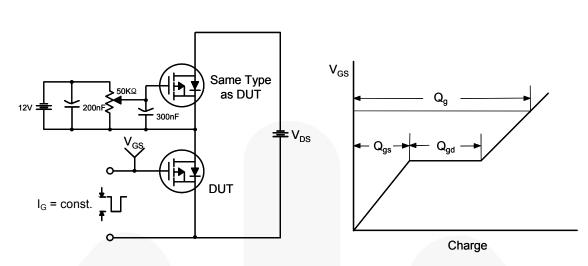


Figure 12. Gate Charge Test Circuit & Waveform

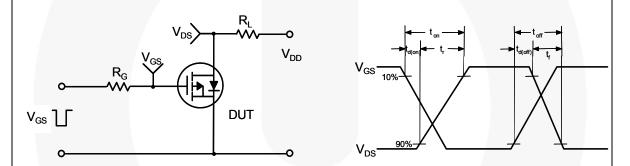


Figure 13. Resistive Switching Test Circuit & Waveforms

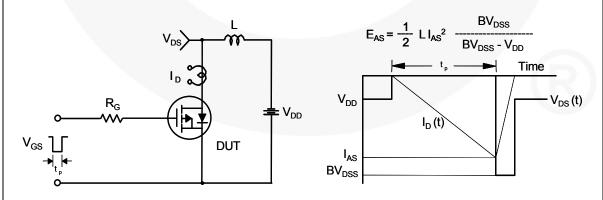
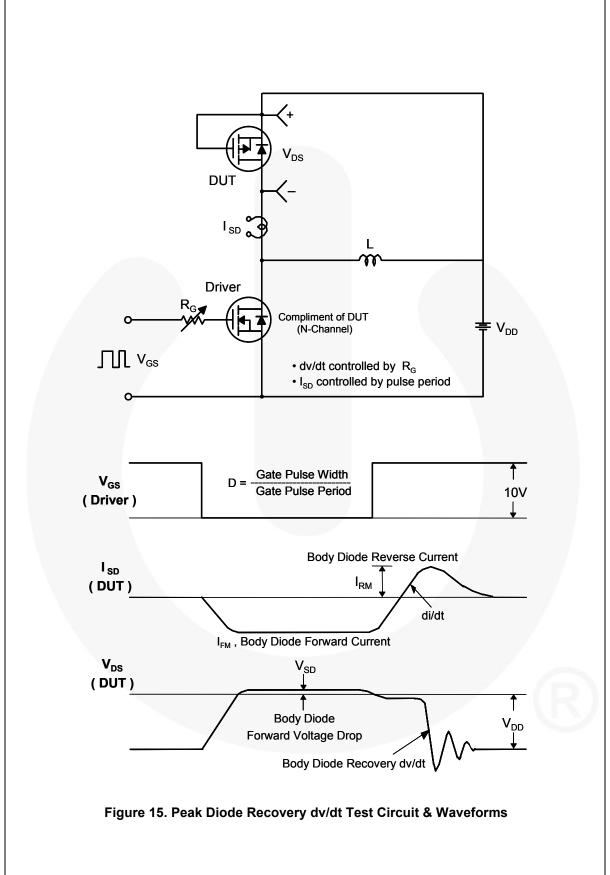
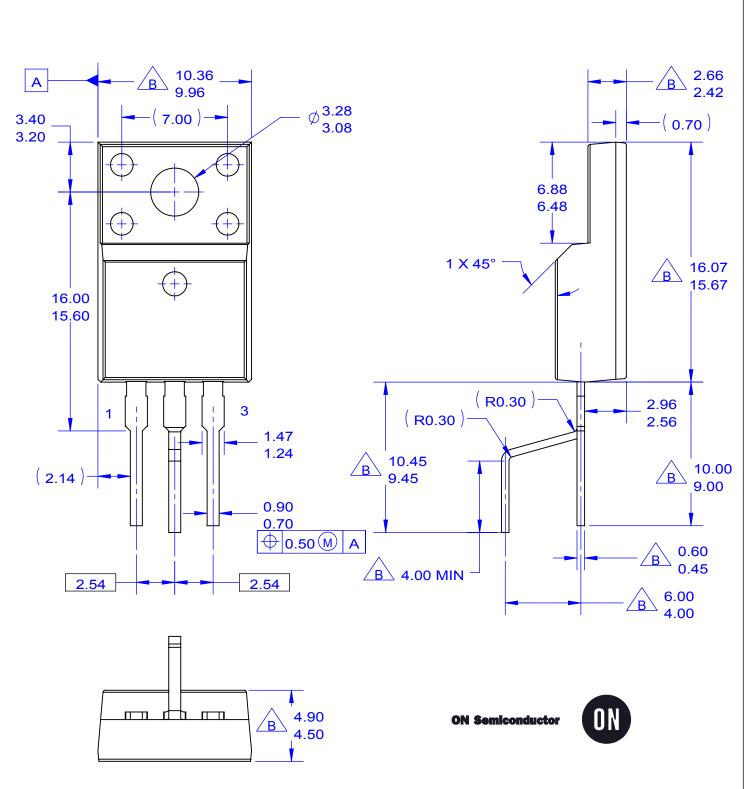


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms





NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO
- EIAJ SC91A.

 B DOES NOT COMPLY EIAJ STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- F. DRAWING FILE NAME: TO220Q03REV2

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

onsemi

FQPF9P25YDTU